

PRELIMINARY DATA SHEET

SKY77433 Front-End Module for WCDMA / HSDPA / HSUPA (Tx 1920-1980 MHz), (Rx 2110-2170 MHz)

Applications

- Digital cellular (WCDMA) handsets

Features

- High Speed Downlink Packet Access (HSDPA)
- High Speed Uplink Packet Access (HSUPA)
- Low quiescent current - 20 mA
- Low current consumption - 500 mA
- Integrated Power Detector
- 16-pad package
- Small profile - 4 mm x 7 mm x 1.05 mm
- Low voltage - 3.1 V to 4.45 V
- Digital enable pad
- Highly integrated, user friendly solution
- InGaP HBT
- Integrated interstage filter and duplexer
- Supports low collector voltage operation
- Requires few external components

Description

The SKY77433 Front-End Module (FEM) is a fully matched, 16-pad surface mount module developed for WCDMA applications. Small and efficient, this WCDMA FEM integrates the interstage filter, the input matching, the power amplifier, the output matching, the power detection, and the duplexer into a single 7 mm x 4 mm x 1.05 mm package.

The SKY77433 meets the stringent spectral requirements of HSDPA standards up to 25.2 dBm output power. The FEM incorporates an InGaP HBT PA and contains circuitry to optimize power detector performance. Different control pads are available to enhance the performance of the FEM at different power levels.

Integration of the RF front-end greatly simplifies the design of the handset radio as all critical matching between the interstage filter, PA, power detection, and duplexer is optimized within the module. By optimizing the efficiency of the InGaP HBT PA MMIC and reducing the RF loss between the integrated components, this FEM achieves current as low as 500 mA at maximum output power (25.2 dBm) that significantly improves the talk time of the WCDMA handset. This small package uses Skyworks' low cost, multi-laminate substrate technology and is approximately half the size of individually packaged component solutions. The SKY77433 front-end module can save handset designers significant board space and design-cycle time.

NEW Skyworks Green™ products are lead (Pb)-free, RoHS (Restriction of Hazardous Substances)-compliant, conform to the EIA/EICTA/JEITA Joint Industry Guide (JIG) Level A guidelines, and are free from antimony trioxide and brominated flame retardants.

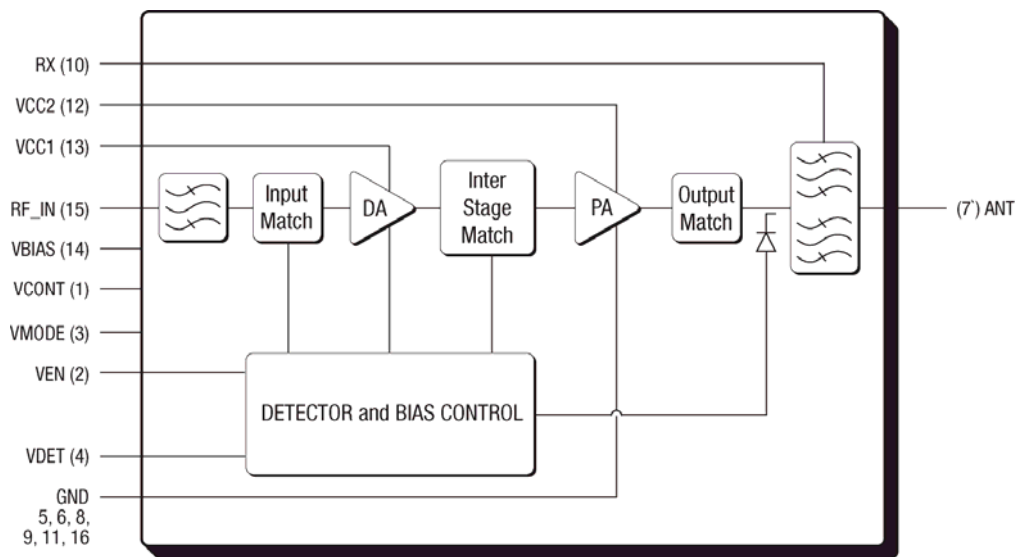



Figure 1. Functional Block Diagram

Electrical Specifications

The following tables list the electrical characteristics of the SKY77433 Front-End Module for WCDMA. Table 1 lists the absolute maximum ratings; Table 2 specifies the recommended operating conditions necessary for achieving the electrical performance listed in Table 3 and Table 4 through Table 7 specifies the standard test configurations in WCDMA, HSDPA, and

HSUPA modes, respectively. Table 8 lists parameters specific to power detection performance over recommended operating conditions, including mismatch at the module antenna port up to a VSWR of 2.5:1 for all phase angles. Table 9 shows nominal duplexer performance.

Table 1. Absolute Maximum Ratings¹

Parameter	Symbol	Minimum	Nominal	Maximum	Unit
RF Input Power	P _{IN}	—	—	10.0	dBm
Supply Voltages	No RF	V _{CC1} , V _{CC2} , V _{BIAS}	3.4	6.0	Volt
	With RF		3.4	4.7	Volt
Bias Control Voltage	V _{CONT}	—	—	2.7	Volt
Mode Control Voltage	V _{MODE}	—	—	3.0	Volts
Enable Control Voltage	V _{EN}	—	—	3.0	Volt
Temperatures	Operating	T _{CASE}	-20	+25	°C
	Storage	T _{STG}	-55	+125	

¹ No damage assuming only one parameter at a time is set to limit with all other parameters set at nominal values.

Table 2. Recommended Operating Conditions

Parameter	Symbol	Minimum	Nominal	Maximum	Unit
Tx Channel Center Frequency	F _{Tx}	1922.4	1950.0	1977.6	MHz
Rx Channel Center Frequency	F _{Rx} = F _{Tx} + 190 MHz	2112.4	2140.0	2167.6	MHz
Supply Voltages	V _{CC1} , V _{CC2}	3.1 ¹	3.4	4.45	Volt
	V _{BIAS}	3.1	3.4	4.45	
Bias Control Voltage	V _{CONT}	0.5	—	1.9	Volt
Mode Control	Low Power Mode (LPM)	V _{MOD_L}	1.5	1.8	Volt
	High Power Mode (HPM)	V _{MOD_H}	0.0	0.0	
Enable Control Setting	Disabled	V _{EN_L}	0.0	0.56	Volt
	Enabled	V _{EN_H}	1.5	2.85	
Operating Temperature	T _{CASE}	-20	+25	+85	°C

¹ For V_{CC} < 3.4 V, maximum output power = P_{MAX2}

Table 3. Electrical Specifications for Nominal Operating Conditions¹ (1 of 2)

WCDMA (Wide Band Code Division Multiple Access)							
Parameter		Symbol	Conditions	Minimum	Typical	Maximum	Unit
Linear Output Power		P _{MID}	V _{CC} ≥ 3.1 V HPM, LPM	16.0	—	—	dBm
		P _{MAX2} ²	V _{CC} ≥ 3.1 V HPM	24.4	—	—	
		P _{MAX1} ²	HPM	25.2	—	—	
Gain	Mid-Power	G _{MID}	LPMP _{MID}	11.0	—	23.0	dB
	High Power	G _{HIGH}	P _{MAX1}	19.5	—	28.5	
Current Consumption	Mid-Power	I _{CC}	LPM P _{MID}	—	—	55	mA
	High Power		P _{MAX1}	—	—	500	
Power Added Efficiency	Mid-Power	PAE _{MID}	LPM P _{MID}	5.3	—	—	%
	High Power	PAE _{HIGH}	P _{MAX1}	19.5	—	—	
Error Vector Magnitude		EVM	—			5	%
Adjacent Channel Leakage Ratio ³	5 MHz	ACLR1	—	—	-40	—	dBc
	10 MHz	ACLR2		—	-54	—	
Harmonic Suppression	Second	2f _{0f}	P _{MAX1}	—	—	-33	dBm
	Third	3f _{0f}		—	—	-33	

Table 3. Electrical Specifications for Nominal Operating Conditions¹ (2 of 2)

[continued] WCDMA (Wide Band Code Division Multiple Access)						
Parameter	Symbol	Conditions	Minimum	Typical	Maximum	Unit
Tx Noise Power in Rx Band	NRx1	P _{MAX1} 869–894 MHz RBW = 3.84 MHz	—	—	-61	dBm
	NRx2	P _{MAX1} 1575.42 MHz RBW = 2.046 MHz	—	—	-100	
	NRx3	P _{MAX1} 1884.5–1879.9 MHz RBW = 3.84 MHz	—	—	-61	
	NRx4	P _{MAX1} 2110–2170 MHz RBW = 3.84 MHz	—	—	-114	
	NRx5	P _{MAX1} 2400–2483.5 MHz RBW = 1.0 MHz	—	—	-90	
	NRx6	P _{MAX1} 921–925 MHz RBW = 100 kHz	—	—	-61	
	NRx7	P _{MAX1} 925–935 MHz RBW = 2.046 MHz	—	—	-61	
	NRx8	P _{MAX1} 1805–1881 MHz RBW = 3.84 MHz	—	—	-72	
	NRx9	P _{MAX1} 1893.5–1919.6 MHz RBW = 3.84 MHz	—	—	-42	
Input Voltage Standing Wave Ratio	VSWR	—	—	—	2:1	
Quiescent Current	I _Q	—	—	—	25	mA
Control Current	I _{CONT}	—	—	—	1	mA
Digital Enable Current	I _{EN}	—	—	—	1	mA
Leakage Current	I _{LEAK}	V _{CC1} , V _{CC2} , V _{BIAS} = 4.45 V V _{CONT} = 0 V V _{EN} = 0 V V _{MODE} = 0 V	—	—	20	μA
Stability (spurious output)	S	8:1 VSWR, all phases	—	—	-65	dBc
Ruggedness – no damage ⁴	R _u	—	10:1	—	—	

¹ Unless otherwise specified: V_{CC} = 3.4 V, Temp. = 25 °C.

² For STC1 WCDMA, STC2 HSDPA, and STC3 HSUPA modes test conditions. For STC4 HSUPA, power backoff = 2.6 dB.

³ ACLR is specified per 3GPP as the ratio of in-band power to adjacent power, both measured in 3.84 MHz bandwidth at specified offsets.

⁴ All phases, time = 10 seconds, continuous WCDMA/HSDPA modulated signal, V_{CC} = 4.7 V, P_O = P_{MAX1} + 1.5 dB, P_{IN_MAX} = +10 dBm.

Table 4. Standard Test Configuration – STC1 WCDMA Mode

Parameter	Level	Spread Code	Spread Factor	I/Q	β_c	β_d	β_{hs}	β_{ec}	β_{ed}	Relative Power (dB)
DPCCH	15 kbps	0	256	Q	8/15	—	—	—	—	-6.547
DPDCH	60 kbps	16	64	I	—	15/15	—	—	—	-1.087

Table 5. Standard Test Configuration – STC2 HSDPA Mode

Parameter	Level	Spread Code	Spread Factor	I/Q	β_c	β_d	β_{hs}	β_{ec}	β_{ed}	Relative Power (dB)
DPCCH	15 kbps	0	256	Q	12/15	—	—	—	—	-7.095
DPDCH	60 kbps	16	64	I	—	15/15	—	—	—	-5.157
HS-DPCCH	15 kbps	64	256	Q	—	—	24/15	—	—	-3.012

Table 6. Standard Test Configuration – STC3 HSUPA Mode

Parameter	Level	Spread Code	Spread Factor	I/Q	β_c	β_d	β_{hs}	β_{ec}	β_{ed}	Relative Power (dB)
DPCCH	15 kbps	0	256	Q	8/15	—	—	—	—	-19.391
DPDCH	960 kbps	1	4	I	—	15/15	—	—	—	-13.931
HS-DPCCH	15 kbps	64	256	Q	—	—	8/15	—	—	-19.391
E-DPCCH	15 kbps	1	256	I	—	—	—	10/15	—	-17.338
E-DPDCH	960 kbps	2	4	I	—	—	—	—	71.5/15	-0.371

Table 7. Standard Test Configuration – STC4 HSUPA Mode

Parameter	Level	Spread Code	Spread Factor	I/Q	β_c	β_d	β_{hs}	β_{ec}	β_{ed}	Relative Power (dB)
DPCCH	15 kbps	0	256	Q	6/15	—	—	—	—	-12.499
DPDCH	960 kbps	1	4	I	—	15/15	—	—	—	-4.540
HS-DPCCH	15 kbps	64	256	Q	—	—	2/15	—	—	-22.041
E-DPCCH	15 kbps	1	256	I	—	—	—	12/15	—	-6.478
E-DPDCH	960 kbps	2	4	I	—	—	—	—	15/15	-4.425

Table 8. Electrical Specifications for Power Detector

<i>Tx Power Detection</i>						
Parameter	Symbol	Conditions	Minimum	Typical	Maximum	Unit
Detector Power Detect Range	P _{DET}		0.0	—	26.0	dBm
Detector Output Range	V _{DET}	3 dBm ≤ P ₀ ≤ 26 dBm	400 (rms)	—	1800 (peak)	mV

Table 9. Nominal Duplexer Performance

<i>Antenna to Rx Parameter</i>						
Parameter	Symbol	Conditions	Minimum	Typical	Maximum	Unit
Insertion Loss	IL _{Rx}	2110 MHz to 2170 MHz	—	—	2.0	dB
Ripple		Each Rx Frequency	-0.5	—	0.5	dB
Attenuation		DC to 12750 MHz	20	—	—	dB
		A _{Rx1}	180 MHz to 200 MHz	40	—	
		A _{Rx2}	703 MHz to 724 MHz	25	—	
		A _{Rx3}	1055 MHz to 1085 MHz	45	—	
		A _{Rx4}	1730 MHz to 1790 MHz	40	—	
	Tx Band	A _{Rx5}	1920 MHz to 1980 MHz	50	—	
		A _{Rx6}	2015 MHz to 2025 MHz	23	—	
		A _{Rx7}	2025 MHz to 2050 MHz	13	—	
		A _{Rx8}	2050 MHz to 2075 MHz	5	—	
		A _{Rx9}	4030 MHz to 4150 MHz	35	—	
	A _{Rx10}	5950 MHz to 6130 MHz	35	—		
VSWR		—	—	—	2.0:1	
Input		—	—	—	30	dBm
Tx Power @ Rx Port		1920 MHz to 1980 MHz P _{MAX1}	—	—	-25	dBm

Evaluation Board Description

The evaluation board is a platform for testing and interfacing design circuitry. To accommodate the interface testing of the SKY77433, the evaluation board schematic and assembly

diagrams are included for preliminary analysis and design. The basic schematic is shown in Figure 2 for the board assembly in Figure 3.

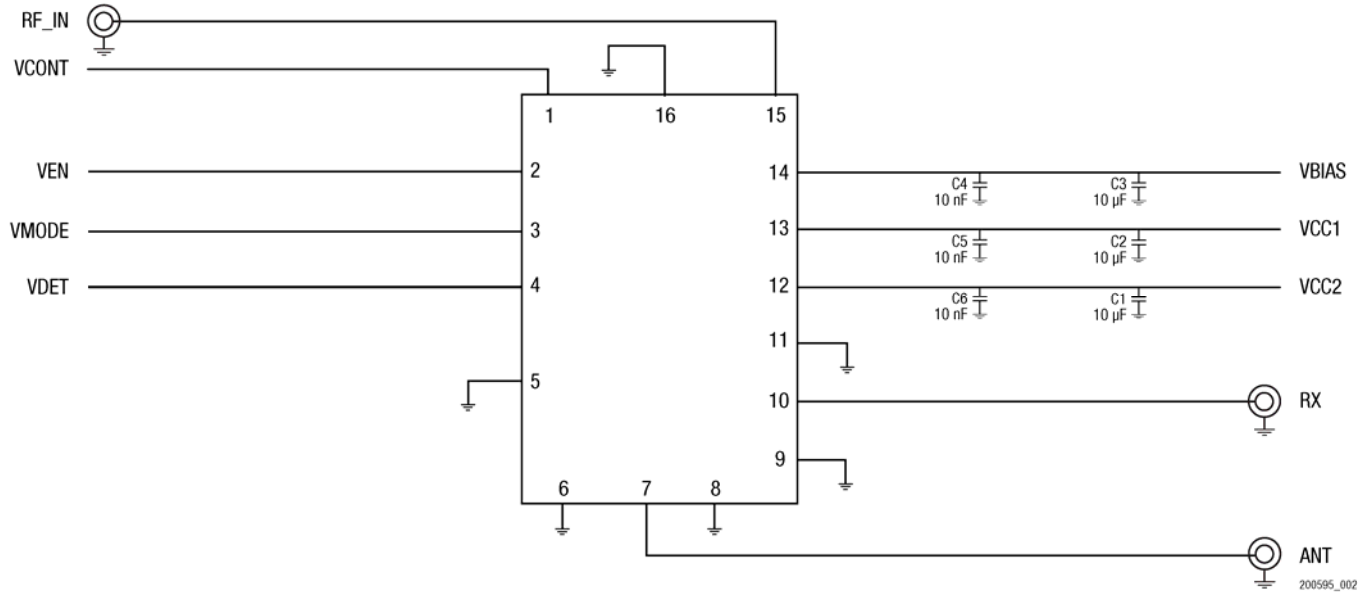


Figure 2. Evaluation Board Schematic Diagram

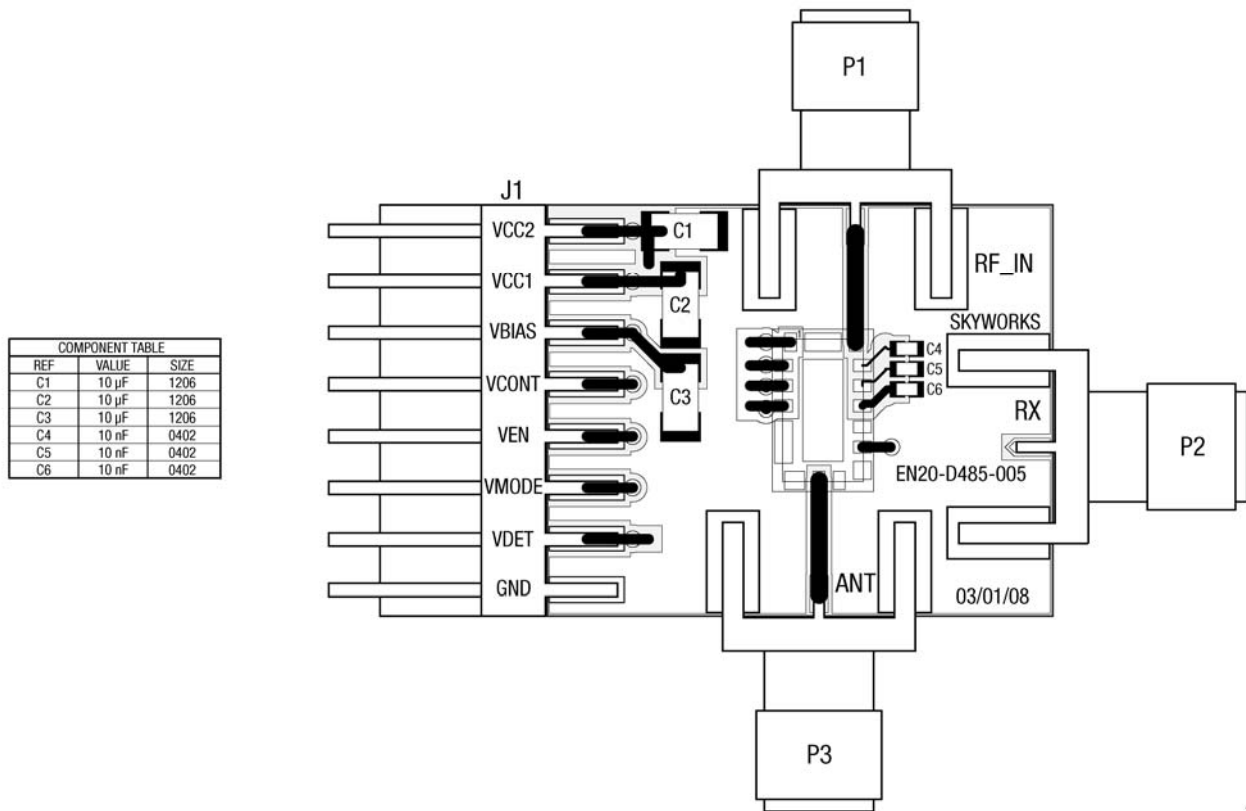
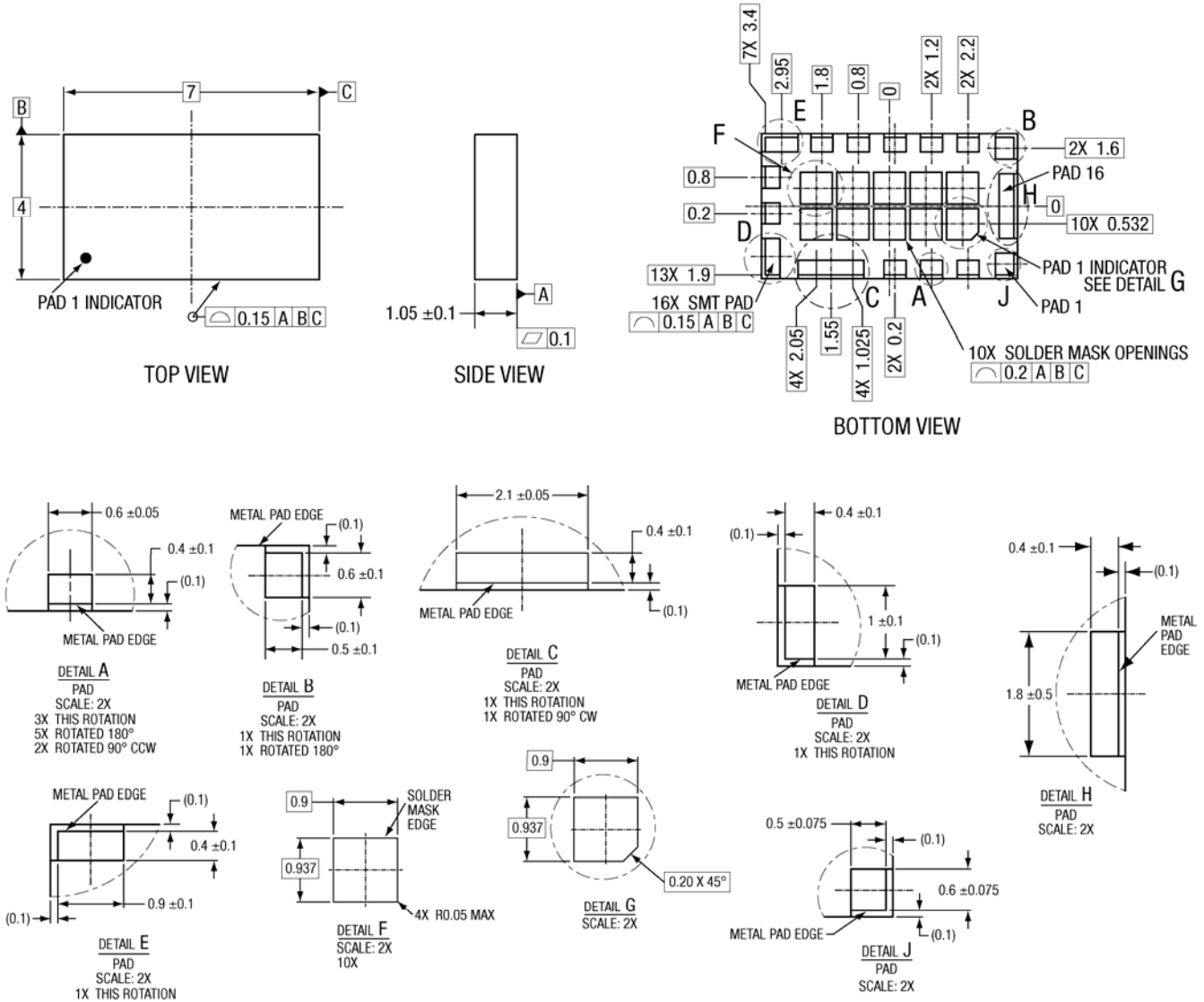


Figure 3. Evaluation Board Assembly Diagram

Package Dimensions

The SKY77433 is a multi-layer laminate base, overmold encapsulated modular package designed for surface-mounted solder attachment to a printed circuit board. Figure 4 is a mechanical drawing of the pad layout for this package. Figure 5

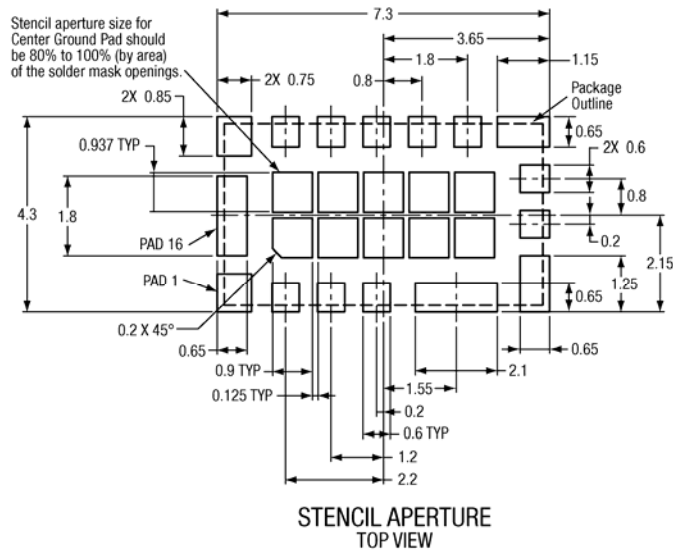
provides a recommended phone board layout footprint for the FEM to help the designer attain optimum thermal conductivity, good grounding, and minimum RF discontinuity for the 50 ohm terminals.



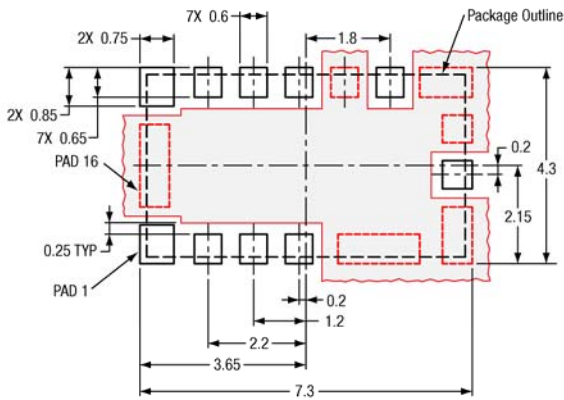
- NOTES: UNLESS OTHERWISE SPECIFIED.
1. DIMENSIONING AND TOLERANCING IN ACCORDANCE WITH ASME Y14.5M-1994.
 2. ALL DIMENSIONS ARE IN MILLIMETERS.
 3. PADS ARE SOLDER MASK DEFINED ON 3 EDGES & METAL DEFINED ON 1 EDGE.

DS00089-2 REV. 1
200595_004

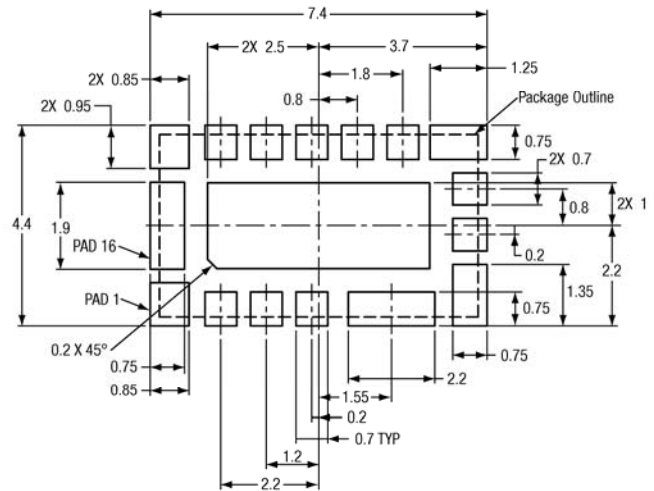
Figure 4. Dimensional Diagram for 7 x 4 x 1.05 mm, 16-Pad Package (All Views) – SKY77433



STENCIL APERTURE
TOP VIEW



METALLIZATION
TOP VIEW



SOLDER MASK OPENING
TOP VIEW

NOTES: UNLESS OTHERWISE SPECIFIED.

1. DIMENSIONING AND TOLERANCING IN ACCORDANCE WITH ASME Y14.5M-1994.
2. ALL DIMENSIONS ARE IN MILLIMETERS.

DS00089-2 REV. 1
200595_005

Figure 5. Phone PCB Layout Footprint for 7 x 4 mm, 16-Pad Package – SKY77433

Package Description

Figure 6 shows each pad name and the pad numbering convention, which starts with pad 1, in the lower left as indicated, and increments counter-clockwise around the package. Figure 7 illustrates typical case markings.

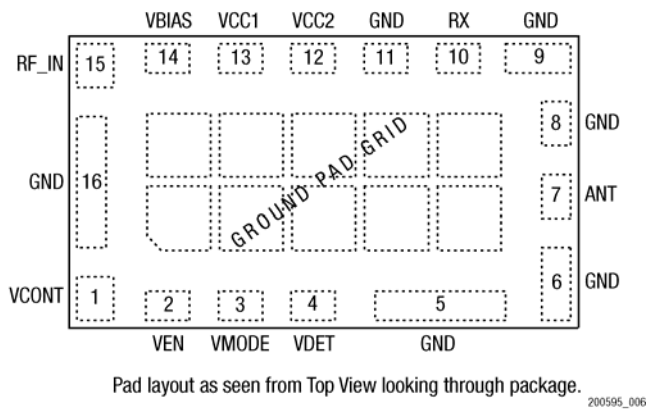
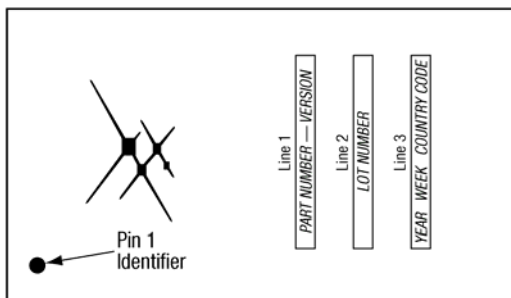


Figure 6. SKY77433 16-Pad Configuration – (Top View)



NOTE: SKY77433
Lines 1, 2, 3 have a maximum of 11 characters
YEAR = Year of Manufacture
WEEK = Week Package Was Sealed
Country Code = Country of Manufacture (MX)

200595_006

Figure 7. Typical Case Markings (Top View)

Package Handling Information

Because of its sensitivity to moisture absorption, this device package is baked and vacuum-packed prior to shipment. Instructions on the shipping container label must be followed regarding exposure to moisture after the container seal is broken, otherwise, problems related to moisture absorption may occur when the part is subjected to high temperature during solder assembly.

The SKY77433 is currently qualified for MSL3/260 °C. Care must be taken when attaching this product, whether it is done manually or in a production solder reflow environment. If the part is attached in a reflow oven, the temperature ramp rate should not exceed 3 °C per second; maximum temperature should not exceed 260 °C. If the part is manually attached, precaution should be taken to insure that the part is not subjected to temperatures exceeding 260 °C for more than 10 seconds. For details on attachment techniques, precautions, and handling procedures recommended by Skyworks, please refer to Skyworks Application Note: *PCB Design and SMT Assembly/Rework*, Document Number 101752. Additional information on standard SMT reflow profiles can also be found in the *JEDEC Standard J-STD-020*.

Production quantities of this product are shipped in the standard tape-and-reel format. For packaging details, refer to Skyworks Application Note: *Tape and Reel – RF Modules*, Document Number 101568.

Electrostatic Discharge Sensitivity (ESD)

To avoid ESD damage, both latent and visible, it is very important that the product assembly and test areas follow the Class 1 ESD handling precautions listed below.

- Personnel Grounding
 - Wrist Straps
 - Conductive Smocks, Gloves and Finger Cots
 - Antistatic ID Badges
- Protective Workstation
 - Dissipative Table Top
 - Protective Test Equipment (Properly Grounded)
 - Grounded Tip Soldering Irons
 - Solder Conductive Suckers
 - Static Sensors
- Facility
 - Relative Humidity Control and Air Ionizers
 - Dissipative Floors (less than 10⁹ Ω to GND)
- Protective Packaging and Transportation
 - Bags and Pouches (Faraday Shield)
 - Protective Tote Boxes (Conductive Static Shielding)
 - Protective Trays
 - Grounded Carts
 - Protective Work Order Holders

Ordering Information

Model Number	Manufacturing Part Number	Product Revision	Package	Operating Temperature
SKY77433	SKY77433		MCM 7 x 4 x 1.05 mm	-20 °C to +85 °C

Revision History

Revision	Date	Description
A	August 29, 2007	Initial Issue – Preliminary Information
B	December 8, 2008	Revise: Features list (p1); Tables 1, 3, 8; Figures 2–5 Add: GREEN tag (p1); Tables 4–7

References

Skyworks Application Note: Tape and Reel – RF Modules, Document Number 101568

Skyworks Application Note: PCB Design and SMT Assembly/Rework, Document Number 101752

JEDEC Standard J-STD-020

© 2007–2008 Skyworks Solutions, Inc. All Rights Reserved.

Information in this document is provided in connection with Skyworks Solutions, Inc. ("Skyworks") products or services. These materials, including the information contained herein, are provided by Skyworks as a service to its customers and may be used for informational purposes only by the customer. Skyworks assumes no responsibility for errors or omissions in these materials or the information contained herein. Skyworks may change its documentation, products, services, specifications or product descriptions at any time, without notice. Skyworks makes no commitment to update the materials or information and shall have no responsibility whatsoever for conflicts, incompatibilities, or other difficulties arising from any future changes.

No license, whether express, implied, by estoppel or otherwise, is granted to any intellectual property rights by this document. Skyworks assumes no liability for any materials, products or information provided hereunder, including the sale, distribution, reproduction or use of Skyworks products, information or materials, except as may be provided in Skyworks Terms and Conditions of Sale.

THE MATERIALS, PRODUCTS AND INFORMATION ARE PROVIDED "AS IS" WITHOUT WARRANTY OF ANY KIND, WHETHER EXPRESS, IMPLIED, STATUTORY, OR OTHERWISE, INCLUDING FITNESS FOR A PARTICULAR PURPOSE OR USE, MERCHANTABILITY, PERFORMANCE, QUALITY OR NON-INFRINGEMENT OF ANY INTELLECTUAL PROPERTY RIGHT; ALL SUCH WARRANTIES ARE HEREBY EXPRESSLY DISCLAIMED. SKYWORKS DOES NOT WARRANT THE ACCURACY OR COMPLETENESS OF THE INFORMATION, TEXT, GRAPHICS OR OTHER ITEMS CONTAINED WITHIN THESE MATERIALS. SKYWORKS SHALL NOT BE LIABLE FOR ANY DAMAGES, INCLUDING BUT NOT LIMITED TO ANY SPECIAL, INDIRECT, INCIDENTAL, STATUTORY, OR CONSEQUENTIAL DAMAGES, INCLUDING WITHOUT LIMITATION, LOST REVENUES OR LOST PROFITS THAT MAY RESULT FROM THE USE OF THE MATERIALS OR INFORMATION, WHETHER OR NOT THE RECIPIENT OF MATERIALS HAS BEEN ADVISED OF THE POSSIBILITY OF SUCH DAMAGE.

Skyworks products are not intended for use in medical, lifesaving or life-sustaining applications, or other equipment in which the failure of the Skyworks products could lead to personal injury, death, physical or environmental damage. Skyworks customers using or selling Skyworks products for use in such applications do so at their own risk and agree to fully indemnify Skyworks for any damages resulting from such improper use or sale.

Customers are responsible for their products and applications using Skyworks products, which may deviate from published specifications as a result of design defects, errors, or operation of products outside of published parameters or design specifications. Customers should include design and operating safeguards to minimize these and other risks. Skyworks assumes no liability for applications assistance, customer product design, or damage to any equipment resulting from the use of Skyworks products outside of stated published specifications or parameters.

Skyworks, the Skyworks symbol, "Breakthrough Simplicity," DCR, Helios, HIP3, Innovation to Go, Intera, iPAC, LIPA, Polar Loop, and System Smart are trademarks or registered trademarks of Skyworks Solutions, Inc., in the United States and other countries. Third-party brands and names are for identification purposes only, and are the property of their respective owners. Additional information, including relevant terms and conditions, posted at www.skyworksinc.com, are incorporated by reference.